

## A B S T R A C T

A wireless IC module according to an embodiment comprises a base substrate, a pair of antenna terminals that are formed on the base substrate and to which an antenna is connected, an IC chip mounted on the base substrate, a first connection line that connects the IC chip and one antenna terminal of the pair of antenna terminals, and a second connection line that connects the IC chip and the other antenna terminal of the pair of antenna terminals. The base substrate has an identification area where a notch for identification of a defective product is formed, and the first connection line is provided across the identification area such that the first connection line is cut when the notch is formed.